

Title (en)

COMPOSITION FOR BONDING, OPTICAL ADHESIVE, AND ADHESIVE FOR PRESSURE SENSOR

Title (de)

ZUSAMMENSETZUNG ZUM VERBINDEN, OPTISCHER HAFTSTOFF UND HAFTSTOFF FÜR DRUCKSENSOR

Title (fr)

COMPOSITION POUR LIAISON, ADHÉSIF POUR APPLICATION OPTIQUE, ET ADHÉSIF POUR CAPTEUR DE PRESSION

Publication

EP 3467070 A4 20200115 (EN)

Application

EP 17802737 A 20170522

Priority

- JP 2016103419 A 20160524
- JP 2017018992 W 20170522

Abstract (en)

[origin: EP3467070A1] Provided is a composition for bonding that forms, after bonding, an adhesive layer that is less likely to undergo shape deformation, and can maintain high adhesion after a reliability test; also provided are an optical adhesive and an adhesive for pressure sensors, both of which comprise the composition. The composition for bonding comprises resin particles. The resin particles have a recovery rate of 20% or less, and a cured product of the composition with a thickness of 250±50 µm has a moisture permeability of 90 g/m² -24 h or less. An adhesive layer formed from the composition for bonding is less likely to undergo shape deformation, and can maintain high adhesion after a reliability test.

IPC 8 full level

C09J 201/00 (2006.01); **C09J 11/08** (2006.01)

CPC (source: CN EP KR US)

C08G 77/20 (2013.01 - US); **C09J 4/00** (2013.01 - EP KR); **C09J 9/00** (2013.01 - KR); **C09J 11/08** (2013.01 - EP US); **C09J 183/04** (2013.01 - CN KR); **C09J 183/06** (2013.01 - US); **C09J 201/00** (2013.01 - EP); **G01L 19/147** (2013.01 - EP US); **C09J 2301/312** (2020.08 - EP KR); **H01L 2224/32225** (2013.01 - EP)

C-Set (source: EP KR US)

C09J 4/00 + C08F 220/32

Citation (search report)

- [E] EP 3375808 A1 20180919 - SEKISUI CHEMICAL CO LTD [JP]
- [X] WO 2009119788 A1 20091001 - SEKISUI CHEMICAL CO LTD [JP], et al
- [X] WO 2015151136 A1 20151008 - KYOCERA CHEM CORP [JP]

Citation (examination)

- JP 2010225625 A 20101007 - SEKISUI CHEMICAL CO LTD
- See also references of WO 2017204145A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 3467070 A1 20190410; **EP 3467070 A4 20200115**; CN 109196072 A 20190111; CN 109196072 B 20220419; CN 114381232 A 20220422; JP 6947631 B2 20211013; JP WO2017204145 A1 20190328; KR 102395931 B1 20220509; KR 20190010551 A 20190130; TW 201816045 A 20180501; TW I756224 B 20220301; US 10961420 B2 20210330; US 2020317972 A1 20201008; WO 2017204145 A1 20171130

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EP 17802737 A 20170522; CN 201780030896 A 20170522; CN 202111635876 A 20170522; JP 2017018992 W 20170522; JP 2017530106 A 20170522; KR 20187032898 A 20170522; TW 106117172 A 20170524; US 201716304193 A 20170522